



### DXT5551P5Q

#### **160V NPN HIGH VOLTAGE TRANSISTOR**

### **Description**

This Bipolar Junction Transistor (BJT) is designed to meet the stringent requirement of Automotive Applications.

#### **Mechanical Data**

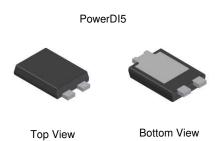
- Case: PowerDI<sup>®</sup>5
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.093 grams (Approximate)

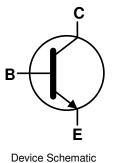
#### **Features**

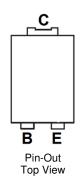
- BV<sub>CEO</sub> > 160V
- I<sub>C</sub> = 0.6A High Continuous Collector Current
- P<sub>D</sub> up to 2.25W
- 43% Smaller Than SOT223; 60% Smaller Than TO252
- Maximum Height just 1.1mm
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

### **Applications**

Telecom Line Driver







### Ordering Information (Note 5)

Part Number	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DXT5551P5Q-13	Automotive	DXT5551	13	16	5.000

- Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
  - 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  - 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  - 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to https://www.diodes.com/quality/.
  - 5. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

### **Marking Information**

DXT5551

**YYWWK** 

PowerDI5

PowerDI is a registered trademark of Diodes Incorporated.



# **Absolute Maximum Ratings** (@ $T_A = +25^{\circ}C$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	180	V
Collector-Emitter Voltage	V <sub>CEO</sub>	160	V
Emitter-Base Voltage	V <sub>EBO</sub>	6	V
Continuous Collector Current	Ic	600	mA

### Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
	(Note 6)		2.25		
Power Dissipation	(Note 7)	$P_{D}$	1.28	W	
	(Note 8)		0.7		
	(Note 6)	R <sub>0JA</sub>	55.5		
Thermal Resistance, Junction to Ambient Air	(Note 7)		97.4	00111	
	(Note 8)		179	°C/W	
Thermal Resistance, Junction to Collector Terminal (Note 9)		$R_{\theta JT}$	30		
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C	

## ESD Ratings (Note 10)

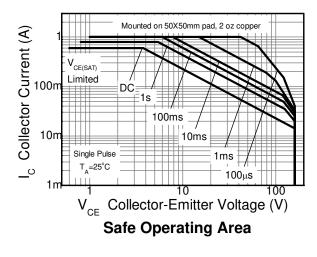
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

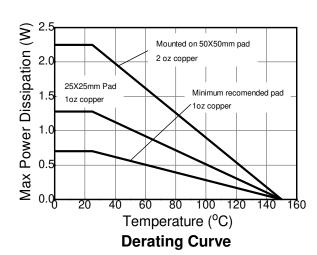
Notes:

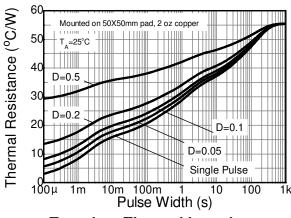
- 6. For a device mounted with the exposed collector pad on 50mm x 50mm 2oz copper that is on a single-sided 1.6mm FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state.
- 7. Same as note (6), except mounted on 25mm x 25mm 1oz copper.
- 8. Same as note (6), except mounted on minimum recommended pad (MRP) layout.
- 9. Thermal resistance from junction to solder-point (on the exposed collector pad).
- 10. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

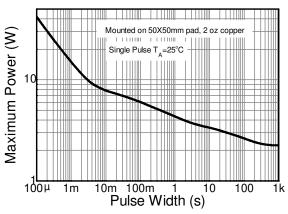


## **Thermal Characteristics and Derating Information**









**Transient Thermal Impedance** 

**Pulse Power Dissipation** 



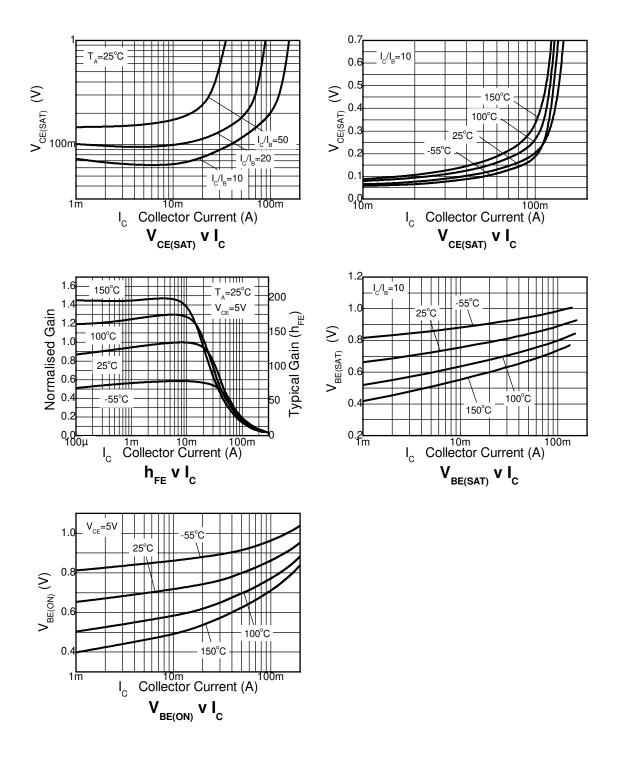
# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	$BV_{CBO}$	180	270	1	<b>V</b>	$I_C = 100\mu A$
Collector-Emitter Breakdown Voltage	$BV_CEO$	160	200	_	٧	I <sub>C</sub> = 1mA
Emitter-Base Breakdown Voltage	$BV_{EBO}$	6.0	7.85	1	<b>V</b>	$I_E = 100\mu A$
Collector Cutoff Current	I <sub>CBO</sub>	_	<1 —	50 50	nΑ μΑ	V <sub>CB</sub> = 120V V <sub>CB</sub> = 120V, T <sub>A</sub> = +100°C
Collector-Emitter Saturation Voltage (Note 11)	V <sub>CE(SAT)</sub>	_	65 115	150 200	mV mV	$I_C = 10mA$ , $I_B = 1mA$ $I_C = 50mA$ , $I_B = 5mA$
Base-Emitter Saturation Voltage (Note 11)	V <sub>BE(SAT)</sub>	_	760 840	1,000 1,200		$I_C = 10mA$ , $I_B = 1mA$ $I_C = 50mA$ , $I_B = 5mA$
DC Current Gain (Note 11)	h <sub>FE</sub>	80 80 30	130 145 65	_ 250 _	l	$V_{CE} = 5V, I_{C} = 1mA$ $V_{CE} = 5V, I_{C} = 10mA$ $V_{CE} = 5V, I_{C} = 50mA$
Transition Frequency	f⊤	_	130	1	MHz	$V_{CE} = 10V, I_{C} = 10mA,$ f = 100MHz
Output Capacitance	Сово	_	_	6	рF	V <sub>CB</sub> = 10V, f = 1MHz
Delay Time	t <sub>D</sub>	_	95	_	ns	
Rise Time Storage Time		_	64		ns	$V_{CC} = 510V, I_{C} = 10mA,$
		_	1,256	_	ns	$I_{B1} = -I_{B2} = 1mA$
Fall Time	t <sub>F</sub>	_	140	_	ns	

Note: 11. Pulse Test: Pulse width  $\leq 300 \mu s$ . Duty cycle  $\leq 2.0\%$ .



# Typical Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

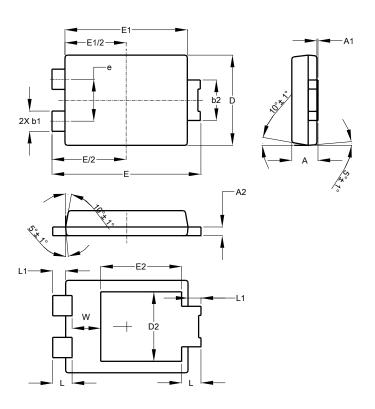




## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI5

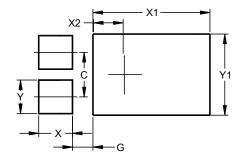


PowerDI5					
Dim	Min	Max	Тур		
Α	1.05	1.15	1.10		
A1	0.00	0.05			
A2	0.33	0.43	0.381		
b1	0.80	0.99	0.89		
b2	1.70	1.88	1.78		
D	3.90	4.05	3.966		
D2			3.054		
Е	6.40	6.60	6.51		
е			1.84		
E1	5.30	5.45	5.37		
E2			3.549		
L	0.75	0.95	0.85		
L1	0.50	0.65	0.57		
W	1.10	1.41	1.255		
All Dimensions in mm					

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI5



Dimensions	Value (in mm)		
С	1.840		
G	0.852		
Х	1.400		
X1	4.860		
X2	1.310		
Y	1.390		
Y1	3.360		

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.



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